

8th Electronics Packaging Technology Conference (EPTC 2006)

6- 8 December 2006, Pan Pacific Hotel, Singapore

CALL FOR PAPERS

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Calendar for
EPTC 2006



About EPTC

The 8th Electronics Packaging Technology Conference (EPTC 2006) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter, sponsored by IEEE CPMT Society with technical sponsorship from IMAPS.

EPTC 2006 will feature technical sessions, short courses and exhibition. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world.

Conference Topics

You are invited to submit an abstract presenting new development in the following categories:

- ❑ **Emerging Packaging Technologies:** Wafer level packaging, 3D integration, embedded passives & actives on substrates, high power modules, SIP and other system integration technologies, bio-packaging, RD-ID and disposable electronics packaging.
- ❑ **Interconnection Technologies:** Gold and copper wire bonding and flip chip (eutectic/lead-free solders) on standard and copper low k wafers, solder replacement flip chip (ICP, ACP, ACF, NCP), under bump metallurgy, microvia and build-up technologies, fine pitch interconnects, nano interconnects.
- ❑ **Manufacturing Technologies:** Sustainable manufacturing processes for environmental and cost improvement. Product/material substitution and recycling. Manufacturing best practices, yield improvement, cost and cycle time reduction, statistical process control.
- ❑ **Materials & Processes:** Advancements in adhesives, encapsulants, underfills, solder alloys, halogen-free materials, dielectrics, ceramics, composites, thin film processes on laminates, nano-materials and processes for packaging.
- ❑ **MEMS Packaging:** Packaging solutions for inertial MEMS - pressure sensors, actuators, microrelays bio-MEMS, RF MEMS - resonators, switches and optical MEMS - switches, crossconnects.
- ❑ **Electrical Modeling & Signal Integrity:** Modeling simulation & measurement for coupling, reflection & switching noise, EMI/EMC analysis on package & subsystems, RF modules, time & frequency domain measurements for advanced modules.
- ❑ **Thermal Characterization & Cooling Solutions:** Modeling & simulation methodology for thermal characterization of advanced packaging, modules & systems. Novel thermal management solutions. Enhanced air & liquid cooling techniques, Hot-spot management.

- ❑ **Mechanical Modeling & Structural Integrity:** Thermo-mechanical modeling. Modeling of delamination, moisture diffusion, hygrostress, drop impact, vibration in modules & systems, measurement of material & interface properties, experimental verification.
- ❑ **Optoelectronics:** Design and simulation of opto-electronic components and modules, development of Gbps and Tbps opto-electronics, photonic interconnects and backplanes, design and development of optical passive components, photonic crystal based devices, development of process and assembly methods for opto-electronic components.
- ❑ **Quality & Reliability:** Component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testing and models, component and systems.

Important Dates

15 June 2006

Submission of abstract

15 July 2006

Notification of Acceptance

15 September 2006

Submission of manuscript

Extended Abstract and Paper Submission

Extended abstracts are solicited to describe original and unpublished work. The abstract should be about 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories for abstract review. All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word with only one single file for each submission. Please limit the file size to a maximum of 2MB.

The abstracts must be received by 15th June 2006. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance and publication instruction by 15th July 2006. The final manuscript for publication in the conference proceedings is due by 15 September 2006.

Outstanding Technical Papers

The conference proceedings is an official IEEE publication. Author(s) of Outstanding Technical Paper(s) will receive an award at the next conference.

Short Courses

The conference program includes full-day short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in subsequent mailings.

Exhibition

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference.

Conference information & contacts:

Website: <http://www.eptc-ieee.net>

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